ITEQ Corporation

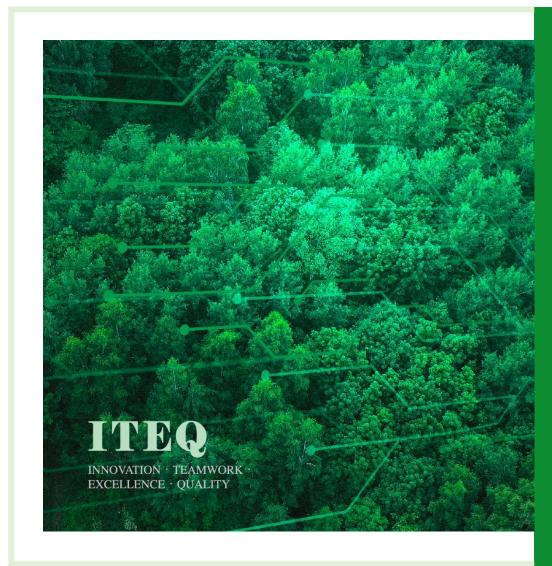
2022 Fourth Quarter Earnings Result

ITEQ

INNOVATION. TEAMWORK. EXCELLENCE. QUALITY

Disclaimer Statement

- This presentation and release contain "forward-looking statements" which may include projections of future results of operations, financial condition or business prospects based on our own information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.





Company Overview



Establishment April 10th, 1997



Headquarters HsinChu, Taiwan



Capital NT\$3,630 million



Employees $\sim 4,000$



Chairman
Dennis Chen



CEO Audrey Tsai



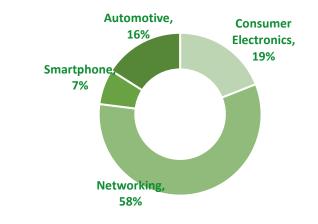
Main Products

Copper Clad Laminate (CCL) & Prepreg (PP) | Masslam service | Flexible CCL

Revenue (NT\$ billion)



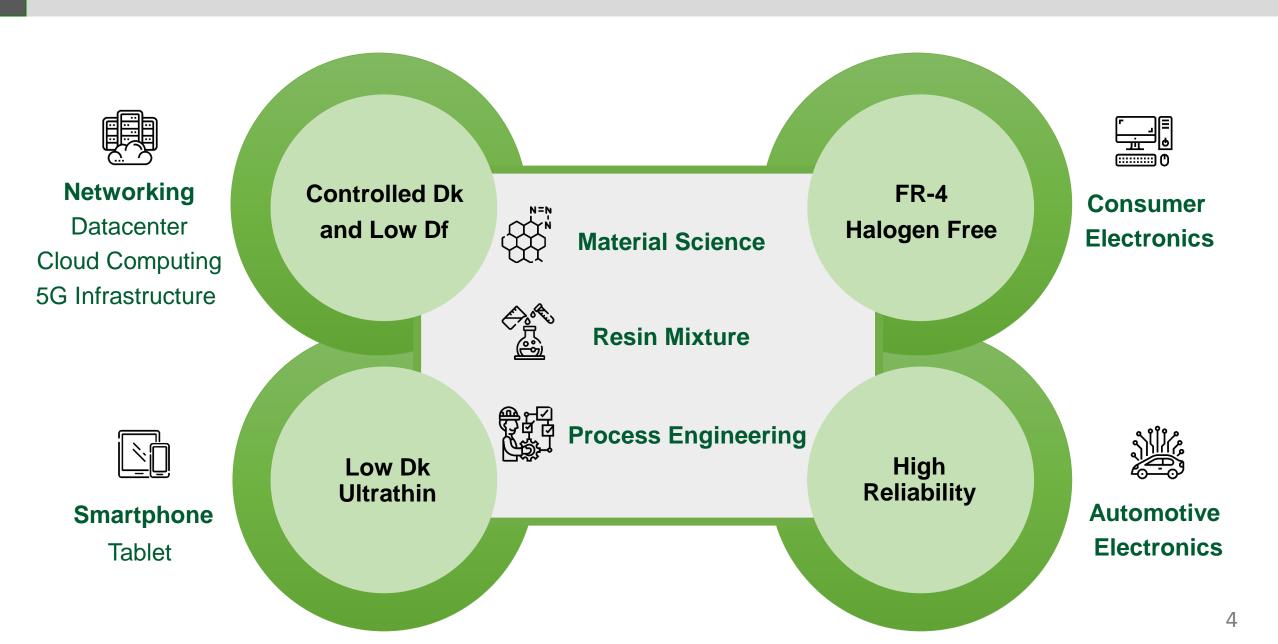
Revenue by Application (FY22)



3

Key Technology Applications







4Q22 & 2022 Financial Results





4Q22 & FY22 Income Statement

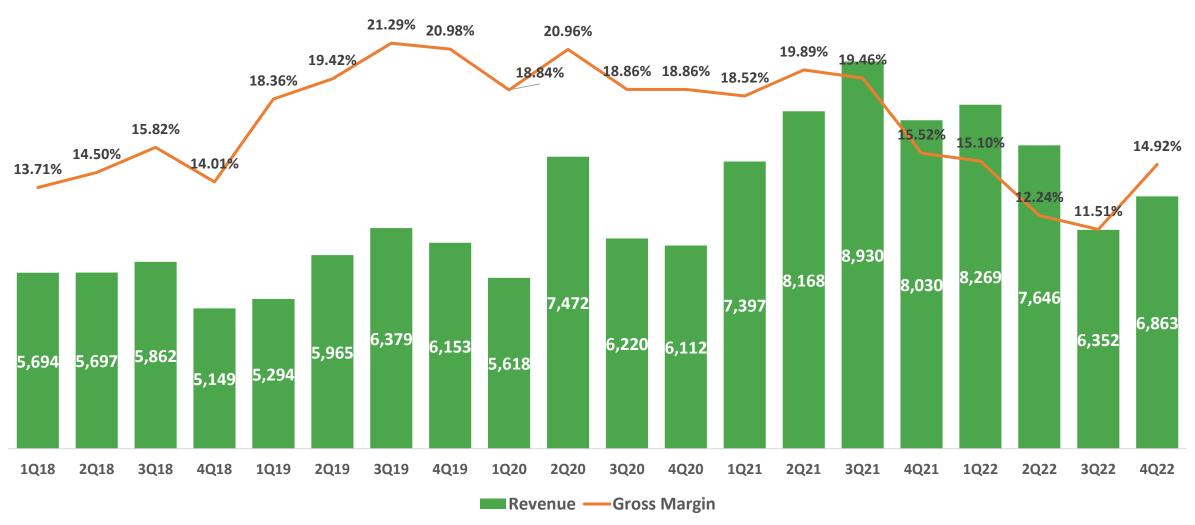


NTD \$Million	4Q22	3Q22	4Q21	QoQ	YoY	2022	2021	YoY
Revenue	6,863	6,352	8,031	8.0%	-14.5%	29,130	32,525	-10.4%
Gross Profit	1,024	731	1,246	40.1%	-17.8%	3,940	5,980	-34.1%
Operating Expense	570	382	543	49.2%	5.0%	2,043	2,160	-5.4%
Operating Profit	454	349	703	30.1%	-35.4%	1,896	3,819	-50.4%
Non-Op Income / Loss	(72)	13	49			419	(5)	
Income before Tax	381	362	752	5.2%	-49.3%	2,315	3,815	-39.3%
Tax Expense	47	85	(55)			460	670	
Net Income to Parent	334	277	807	20.6%	-58.6%	1,855	3,145	-41.0%
EPS(NT\$)	0.92	0.74	2.11	24.3%	-56.4%	4.94	9.00	-45.1%
Key Financial Ratio								
Gross Margin	14.92%	11.51%	15.52%			13.52%	18.38%	
Operating Expense Ratio	8.31%	6.01%	6.76%			7.01%	6.64%	
Operating Margin	6.60%	5.49%	8.75%			6.51%	11.74%	
Effective Tax Rate	12.34%	23.48%	-7.31%			19.87%	17.56%	
Net Margin	4.87%	4.36%	10.05%			6.37%	9.67%	
						Luuuuui		

Revenue & Gross Margin Rate

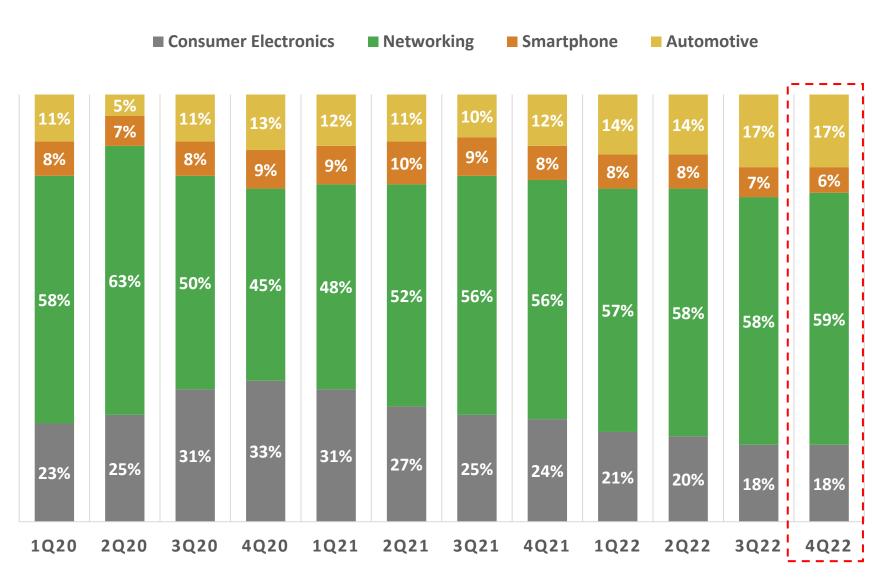


(Million \$NTD)



1Q20~4Q22 Product Mix





4Q22 Product Growth %	QoQ	YoY		
Automotive	+8.0%	+21.1%		
Smartphone	-7.4%	-35.9%		
Networking	+9.9%	-10.0%		
Consumer Electronics	+8.0%	-35.9%		

4Q22 Balance Sheet



	r		
NTD \$Million	4Q22	3Q22	4Q21
Total Assets	33,383	32,523	36,237
Cash	5,214	4,310	4,423
Marketable Securities	3	5	5
NR / AR	12,119	12,315	13,260
Inventories	2,731	2,579	5,167
Fixed Assets	11,102	11,166	11,078
Total Liabilities	13,272	12,525	14,922
Short-term Debt	2,633	3,521	2,131
NP/AP	5,926	3,954	7,121
Long-term Debt	1,677	1,477	-
Total Equity	20,111	19,998	21,315
Key Financial Index			
Days Sales Outstanding	159	154	136
Days Sales of Inventory	62	58	62
Days Payable Outstanding	95	77	83
ROE (%)	8.96	11.30	18.12
ROA (%)	5.57	6.99	10.37
Debt ratio (%)	39.76	38.50	41.18

2016 – 2022 Dividend Policy



Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2016	3.13	2.5	2.5	80%
2017	4.11	3.1	3.1	75 %
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%
2020	8.19	5.0	5.0	61%
2021	9.00	5.0	5.0	56%
2022	4.94	3.0	3.0	61%

^{*}New shares issuance of 30 million common shares concluded on March 31st 2020

^{**}New shares issuance of 50 million common shares concluded on September 2nd 2021

^{***}Factoring in the repurchase and cancellation of 20 million shares in 3Q22; current total outstanding common share: 363 million



Growth Strategy Blueprint

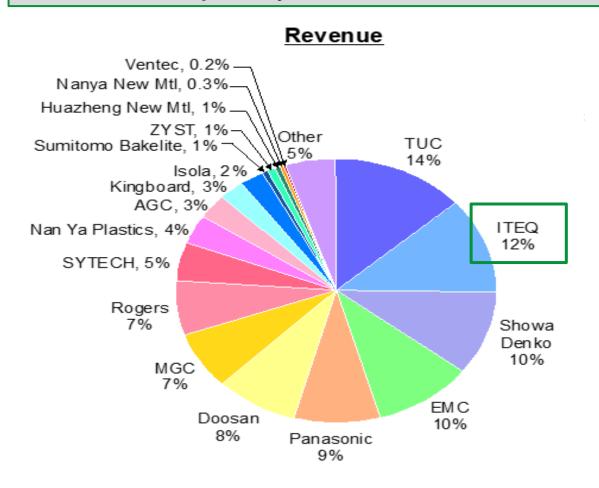




Market Share Leader in Specialty Laminate



2021 WW Specialty Laminate Market Share



Total: \$4.65Bn (\$USD)

ITEQ: Leading CCL supplier

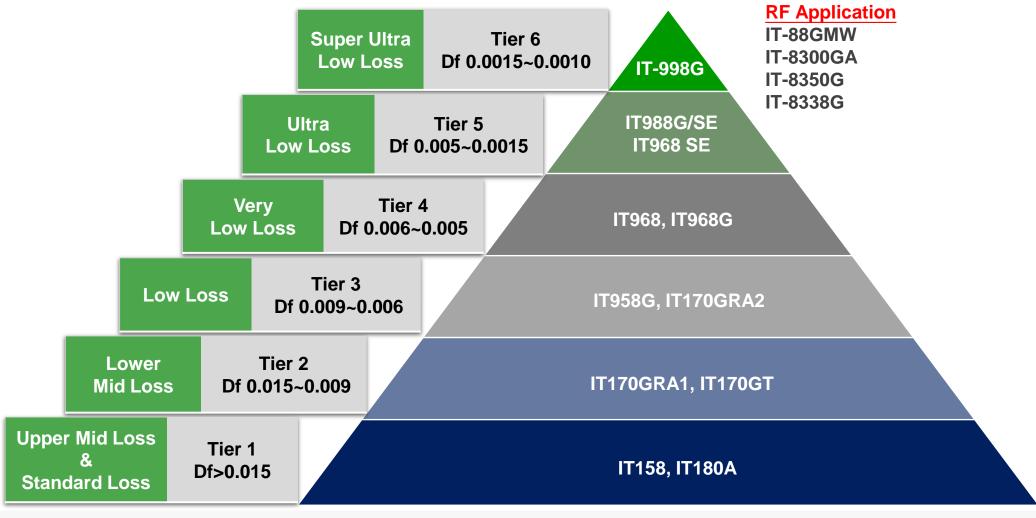
- Worldwide top supplier in high speed / frequency laminate
- Cutting-edge technology with MP track record
- Secular growth momentum in 5G network and data center opportunities
- Rising EV market to boost demand for high speed / frequency automotive CCL



^{*}Specialty Laminate includes: High speed, package substrate, RF Source: Prismark Report, 2022/05

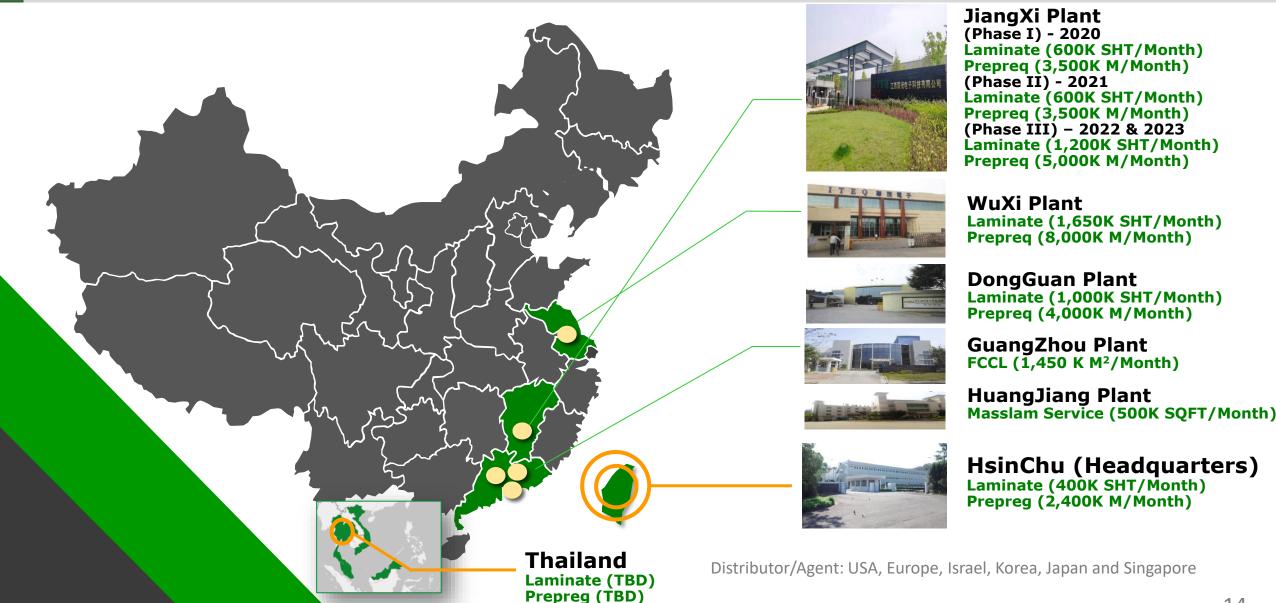
Well-Expanded Product Line

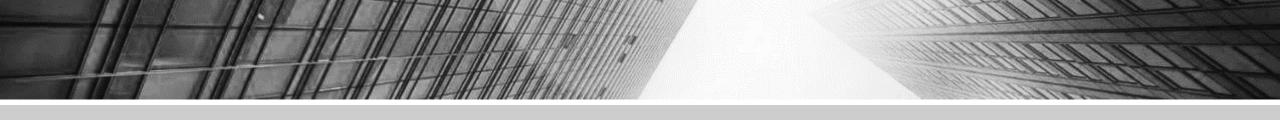




- The need for 5G commercialization and server upgrade to expedite the growth of high speed / frequency material demand
- ITEQ's market share in high speed / frequency material to uplift robustly

Manufacturing Site & Capacity – Expansion PlaniteQ





Market Trend & Growth Drivers





Datacenter Server Platform Upgrade



		Platform	Purley		Whitley	Eagle Stream		Birch Stream
	Intel	CPU	Skylake	Cascade Lake	Ice lake	Sapphire Rapids	Emerald Rapids	Granite Rapids
		Nano Process	14 nm	14 nm+	10 nm	Intel 7	Intel 7	Intel 3
		PCle Gen	PCle 3.0	PCle 3.0	PCle 4.0	PCIe 5.0	PCle 5.0	TBA
		MP Time	2017 Q3	2019 Q3	2021 Q1	2023 H1	2023	2024
ı		CCL Material	Mid Loss	Mid Loss	Low Loss	Very Low Loss	Very Low Loss	TBD
		Layer count	8 to 12	8 to 12	12 to 16	16 to 20	16 to 20	TBD







Datacenter Equipment Cyclical Upgrade to Drive the Following;

- Corresponding CCL material upgrade
- Increase consumption and layer counts for CCL

Advanced Auto Application Opportunities



Green Power/EV



- Energy Conservation
- Power Charging
- High Current & Voltage
- Heavy Cu

High Tg material

Internet of Vehicle

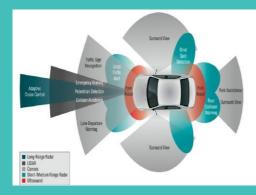


- Infotainment
- Networking

HDI

High Speed Material

Active Safety



- Active Safety System
- ADAS
- Radar
- Antenna Module

High Speed Material

High Frequency Material

Autonomous Driving



- HPC
- Graphic Processing
- Automated Driving Control Module

HDI

High Speed Material

- EV, IoV and Active Safety to boost demand for high performance automotive CCL
- PCB usage for EV is 3 folds of conventional gasoline vehicle

HDI New Product: Resin Coated Copper (RCC)



Resin Coated Copper (RCC)

✓ Glass-free solution which enables further thickness reduction of dielectric layer while satisfies the needs towards fine-line pattern design and hybrid HDI/Substrate-Like PCB production.

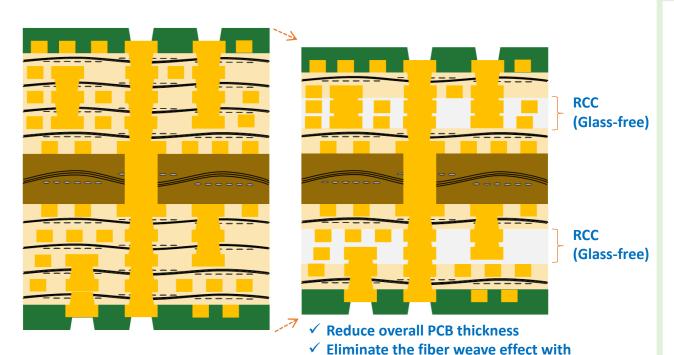


Dielectric Layer : 10~50um ※ Available for thickness up to 150um

Conductors: Copper Foil

enhanced reliability of signal transmission





ITEQ RCC Advantages

Glass-Free

Reduce thickness of the dielectric layer and overcome minimum thickness constraints (15-20um)

Reduce Material Costs

Copper foil + glass fiber + resin \rightarrow Copper foil + resin; replace traditional stacking

Simplify PCB Lamination process

Combine the processes of PP/Copper foil stack-up into one

Better Dielectric Constant (Dk) and Impedance Control

RCC uses pure glue material enabling stable dielectric constant

Better Laser Processability

RCC is a glass fiber free material, which is easier to form holes through laser drilling with more stable Via quality

